



# iEDX-150 $\mu$ T

## High Performance Coating Thickness Analyzer



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X-ray tube	• Mo/Rh/W/Ag Target(Option), 50kVp, 1mA
Detection System	• SDD (Silicon Drift Detector)
Energy Resolution	• 125eV FWHM at Mn K $\alpha$
Collimator	• Poly capillary optics (50~100 $\mu$ m)
Detection Element	• Al(13) – U(92)
Sample Type	• Solid / Liquid / Powder, Multi-Layer
Size of the sample chamber	• 390mm X 410mm X 100mm (W x D x H)
Key Features	<ul style="list-style-type: none"><li>• Auto / Manual Stage Mode</li><li>• Plating thickness measurement general, Rh, Pd, Au, Ag, Sn, Ni</li><li>• Film thickness measurement of multilayer thin films. (up to 5 Layer)</li></ul>
Camera Magnification	• 40~80 x
Safety	• 3 point interlock
Type of Report	<ul style="list-style-type: none"><li>• Excel, PDF / output</li><li>• Custom form</li></ul>
Key Benefits	<ul style="list-style-type: none"><li>• Micro focused measuring point((70<math>\mu</math>m) using capillary optics</li><li>• Film thickness measurement of multilayer thin films. (up to 5 Layer)</li><li>• Convenient stage control</li><li>• Multi-point measurement possible</li><li>• Remote Support by on line</li></ul>
Application	<ul style="list-style-type: none"><li>• Plating thickness measurement special, ENEPIG, Pd-Ni, Rh etc.</li><li>• Plating analysis automobile parts, Electronic circuit board (PCB), Such as a capacitor</li><li>• Analysis of single-layer, Multi-layer, Alloy plating</li><li>• Thickness with Composition Ratio can be measure on time in alloy plating</li></ul>